

01-28-02

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JC984 U.S. PTO
01/24/02

Docket No. A5597/T41100

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Box Patent Application
Commissioner of Patents and Trademarks
Washington, D.C. 20231JC925 U.S. PTO
10/05/014
01/24/02Re: Inventor(s): Padmanabhan Krishnaraj et al.
Title: IN SITU APPLICATION OF ETCH BACK FOR IMPROVED DEPOSITION INTO HIGH-ASPECT-RATIO FEATURES

Transmitted herewith is the patent application identified above, including:

- ☒ Specification, claims and abstract, totaling 22 pages.
☒ Application Data Sheet
☒ Drawings totaling 3 pages, Formal ☒ Informal.
☒ Combined Declaration and Power of Attorney.
☒ Assignment of the invention to **Applied Materials, Inc.**
☒ Assignment Recordation Cover Sheet
☒ Information Disclosure Statement and copies of 16 cited references

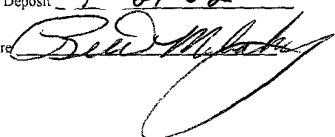
FEE CALCULATION					
Fee Items	Claims Filed	Included With Basic Fee	Extra Claims	Fee Rate	Total
Total Claims	23	-20 =	3	X\$18.00	\$ 54.00
Independent Claims	6	-3 =	3	X\$84.00	\$ 252.00
Basic Filing Fee				\$740.00	\$ 740.00
TOTAL FEES					\$1,046.00

- ☒ The Commissioner is hereby authorized to charge \$1,046.00 to Deposit Account No. 50-1074.
- ☒ The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account No. 50-1074. A duplicate copy of this transmittal is enclosed.
- ☒ Please address all future correspondence to:
- PATENT COUNSEL**
APPLIED MATERIALS, INC.
Legal Affairs Department
P.O. BOX 450A
Santa Clara, CA. 95052

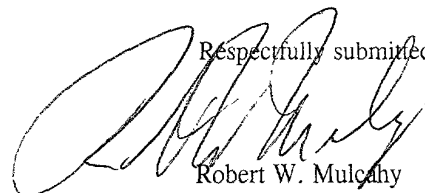
I hereby certify that this correspondence is being deposited with the United States Postal Service as express mail in an envelope addressed to Commissioner of Patents and Trademarks, Washington, D.C. 20231

Express Mail Receipt No. EV04983424345Date of Deposit 1-24-02

Signature



Respectfully submitted,

Robert W. Mulcahy
Registration No. 25,436